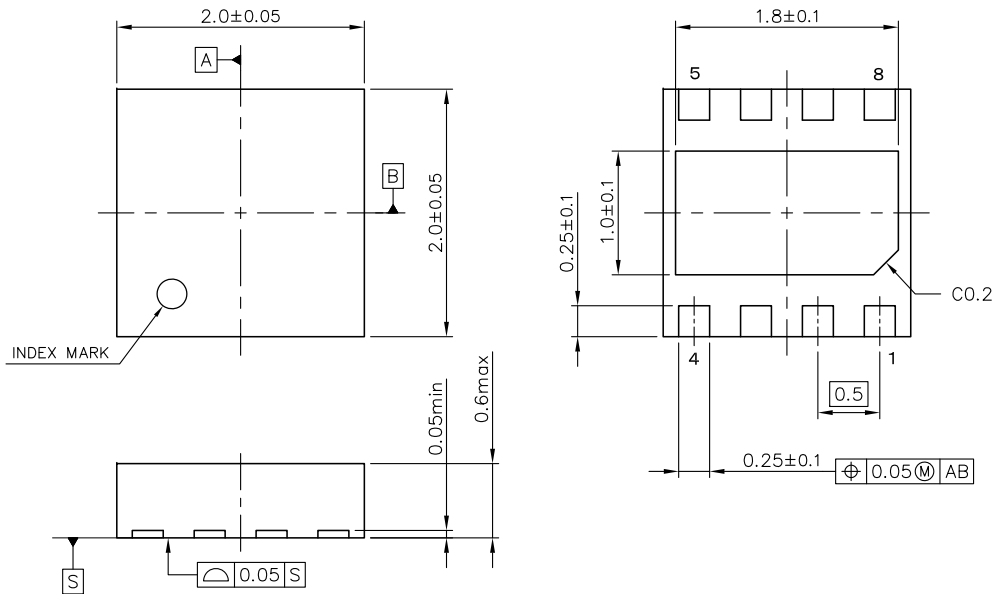


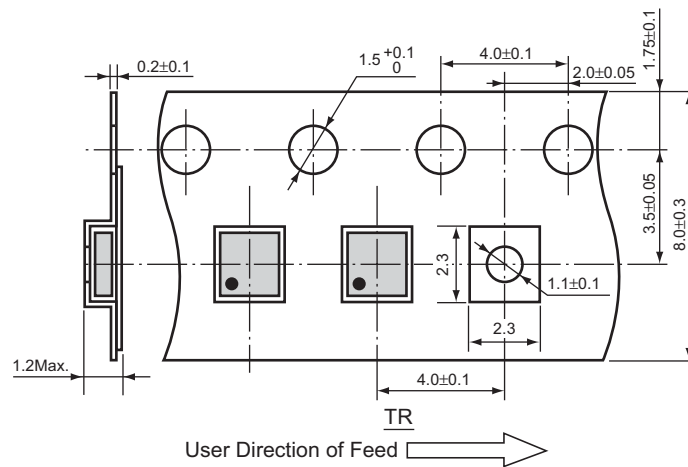
• DFN(PLP)2020-8

Unit: mm

PACKAGE DIMENSIONS

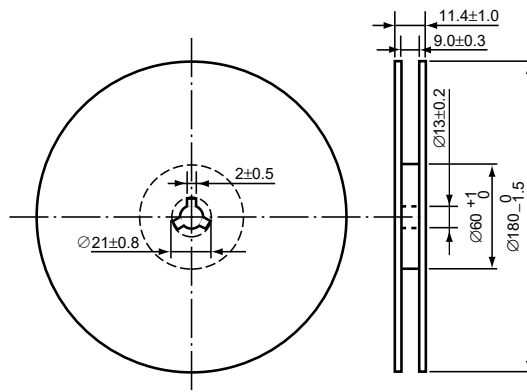


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-08Bc)

(1reel=5,000pcs)



POWER DISSIPATION (DFN(PLP)2020-8)

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51. Refer to the data sheet for the power dissipation of each product.

Measurement Conditions

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.3 mm × 23 pcs

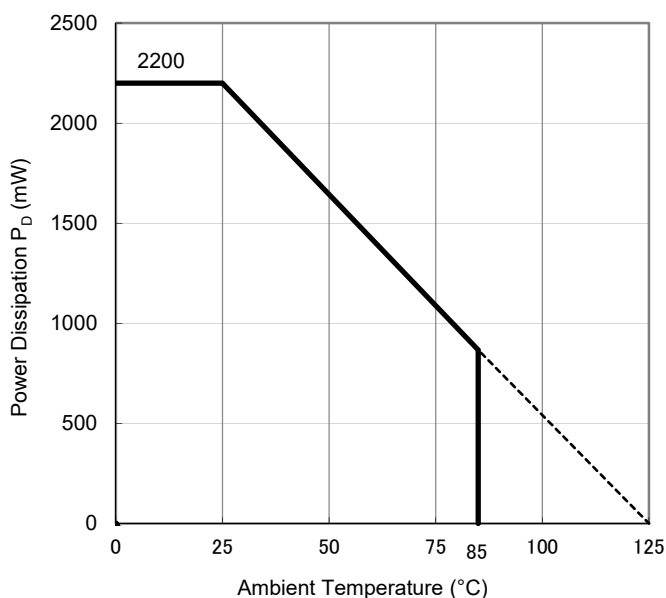
Measurement Result

(Ta = 25°C, Tjmax = 125°C)

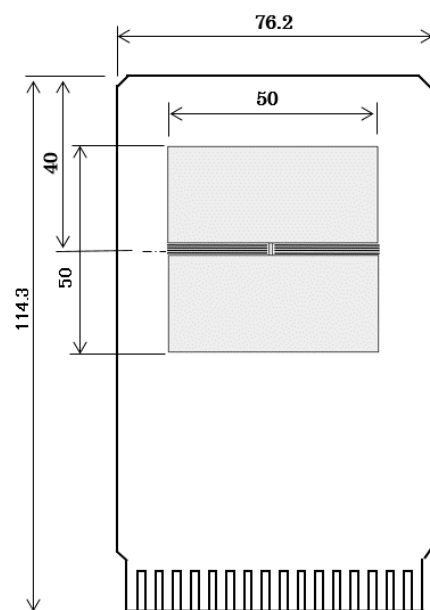
Item	Measurement Result
Power Dissipation	1800 to 2200 mW
Thermal Resistance (θ_{ja})	θ_{ja} = 45 to 53°C/W
Thermal Characterization Parameter (ψ_{jt})	ψ_{jt} = 14 to 27°C/W

θ_{ja} : Junction-to-Ambient Thermal Resistance

ψ_{jt} : Junction-to-Top Thermal Characterization Parameter



Reference Data: 2200 mW
Power Dissipation vs. Ambient Temperature



Measurement Board Pattern

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51. Refer to the data sheet for the power dissipation of each product.

Measurement Conditions

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.3 mm × 23 pcs

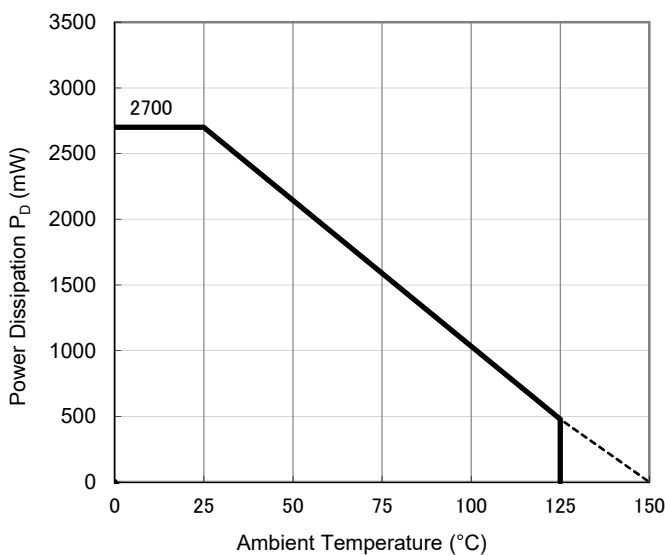
Measurement Result

(Ta = 25°C, Tjmax = 150°C)

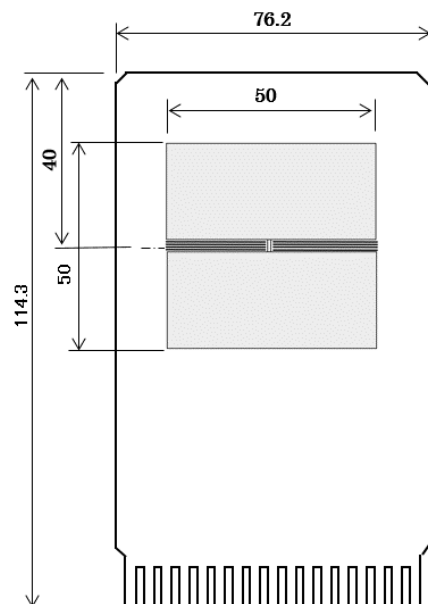
Item	Measurement Result
Power Dissipation	2300 to 2700 mW
Thermal Resistance (θ_{ja})	$\theta_{ja} = 45$ to 53°C/W
Thermal Characterization Parameter (ψ_{jt})	$\psi_{jt} = 14$ to 27°C/W

θ_{ja} : Junction-to-Ambient Thermal Resistance

ψ_{jt} : Junction-to-Top Thermal Characterization Parameter

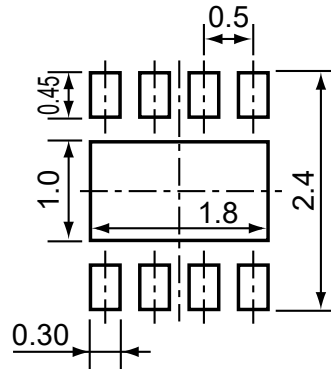


Reference Data: 2700 mW
Power Dissipation vs. Ambient Temperature



Measurement Board Pattern

RECOMMENDED LAND PATTERN



Unit: mm